

CLAIMS

What is claimed is:

1. A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, using a cage having an open side, comprising:

providing a cage enclosing at least two sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and attaching the cage to the substrate, the cage connecting the at least one outer lead of the outer leads of the stacked plurality of primary integrated circuit packages to the at least one conductive bus of the plurality of spaced transverse conductive buses.

2. The method of claim 1, wherein providing a cage further comprises:
providing a cage enclosing more than the at least two sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and
attaching the cage to the substrate, the cage connecting the at least one outer lead of the outer leads of the stacked plurality of primary integrated circuit packages to the at least one conductive bus of the plurality of spaced transverse conductive buses.

3. A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, comprising:
providing a cage enclosing at least two sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and
attaching the cage to the substrate, the cage connecting the at least one outer lead of the outer leads of the stacked plurality of primary integrated circuit packages to the at least one conductive bus of the plurality of spaced transverse conductive buses.

4. A method for connecting a horizontally stacked plurality of primary integrated circuit packages on a substrate having a plurality of circuits thereon, each primary integrated circuit package having a plurality of outer leads and having a plurality of sides, comprising: providing a cage enclosing at least three sides of the plurality of sides of each primary integrated circuit package of the stacked plurality of primary integrated circuit packages; and attaching the cage to the substrate using one of adhesive and snap pins fitting in holes in the substrate, the cage connecting the at least one outer lead of the outer leads of the stacked plurality of primary integrated circuit packages to the at least one conductive bus of the plurality of spaced transverse conductive buses, a portion of the semi-continuous flexible tape located within the cage.